PMP10351 REV B Bill of Materials

Designator	Quantity	Value	PartNumber	Manufacturer	Description	PackageReference
IPCB1	1		PMP10351	Any	Printed Circuit Board	
C1	1	15uF	EEUED2G150	Panasonic	CAP, AL, 15uF, 400V, +/-20%, 1.909859 ohm, TH	12.5x20
C2	1	33uF	EEUED2G330S	Panasonic	CAP, AL, 33 µF, 400 V, +/- 20%, 0.868117 ohm, TH	16x20
C3	1	0.1uF	B32922C3104M	EPCOS Inc	CAP, Film, 0.1 µF, 630 V, +/- 20%, TH	B32922_10.5mm
C4, C5	2	470uF	16ZLG470MEFC8X16	Rubycon	CAP, AL, 470 µF, 16 V, +/- 20%, 0.028 ohm, TH	TH, 2-Leads, Body 8x16mm
C6	1	1uF	GRM188R61E105KA12D	MuRata	CAP, CERM, 1 µF, 25 V, +/- 10%, X5R, 0603	0603
C7	1	10uF	GRM21BR61E106MA73	MuRata	CAP, CERM, 10 µF, 25 V, +/- 20%, X5R, 0805	0805
C8	1	2200pF	DE2E3KY222MA2BM01	MuRata	CAP, CERM, 2200pF, 250V, +/-20%, KY, Radial D8x5mm	Radial D8x5mm
C9	1	4.7uF	GRM319R61H475KA12	MuRata	CAP, CERM, 4.7 µF, 50 V, +/- 10%, X5R, 1206	1206
D1	1	1.1V	DF1506S-T	Diodes Inc.	Diode, Switching-Bridge, 600V, 1.5A, DF-S	DF-S
D2	1	100V	SMCJ100A	Littelfuse	Diode, TVS, Uni, 100V, 1500W, SMC	SMC
D3	1	1.05V	MURA160T3G	ON Semiconductor	Diode, Ultrafast, 600V, 1A, SMA	SMA
D4	1	100V	VF40100C-E3/4W	Vishay-Semiconductor	Diode, Schottky, 100V, 20A, TH	TO-220AB
D5	1	200V	BAS21-TP		en Diode, P-N, 200V, 200A, SOT-23	SOT-23
F1	1		37212000001	Littelfuse	Fuse, 2A, 250V, TH	TR5 fuse 8.5mm DIA
L1	1	33uH	CDRH6D28NP-330NC	Sumida	Inductor, Shielded Drum Core, Ferrite, 33uH, 0.97A, 0.165 ohm, SMD	CDRH6D28
L2	1	4000uH	744821240	Wurth Elektronik eiSos	Coupled inductor, 4000uH, 1.5A, 0.14 ohm, +/-30%, TH	15 x 18 x 7.5mm
L3	1	50 ohm	HI1206T500R-10		cts Ferrite Bead, 50 ohm @ 100MHz, 6A, 1206	1206
Q1	1	600V	TK5P60W_RVQ	Toshiba	MOSFET, N-CH, 600V, 5.4A, DPAK	DPAK
R1	1	24	CRCW201024R0JNEF	Vishay-Dale	RES, 24 ohm, 5%, 0.75W, 2010	2010
R2	1	20	CRCW060320R0JNEA	Vishay-Dale	RES, 20, 5%, 0.1 W, 0603	0603
R3	1	82.5k	CRCW040282K5FKED	Vishay-Dale	RES, 82.5 k, 1%, 0.063 W, 0402	0402
R4	1	1.00k	CRCW04021K00FKED	Vishay-Dale	RES, 1.00 k, 1%, 0.063 W, 0402	0402
R5	1	23.7k	CRCW040223K7FKED	Vishay-Dale	RES, 23.7 k, 1%, 0.063 W, 0402	0402
R6	1	0.51	CRM0805-FX-R510ELF	Bourns	RES, 0.51 ohm, 1%, 0.25W, 0805	0805
R7	1	DNP	N/A	N/A	Do Not Populate	0603
R100	1	4.99k	CRCW04024K99FKED	Vishay-Dale	RES, 4.99 k, 1%, 0.063 W, 0402	0402
T1	1	400 uH	G144071LF	GCI Technologies	Transformer, 400 uH, TH	THD, 8-Leads, Body 21x21mm, Pitch 5mm
TP1, TP2	2	White	5012	Keystone	Test Point, Multipurpose, White, TH	White Multipurpose Testpoint
TP3	1	Red	5010	Keystone	Test Point, Multipurpose, Red, TH	Red Multipurpose Testpoint
TP4	1	Black	5011	Keystone	Test Point, Multipurpose, Black, TH	Black Multipurpose Testpoint
U1	1		UCC28713D	Texas Instruments	Constant-Voltage, Constant-Current Controller With Primary-Side Regulation, D0007A	D0007A

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